25K606

Silicon N Channel Junction Type

For high-frequency amplification

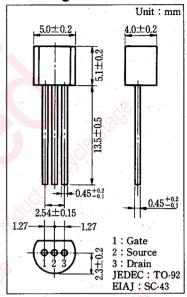
■ Features

- •Large power gain PG
- •Low noise figure NF
- •Low small-signal short-circuit input capacitance Ciss
- •Ideal for front ends of FN tuners

■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit
Gate-Drain Voltage	V_{GDO}	30	V
Drain Current	I_{D}	20	mA
Gate Current	I_G	10	mA
Power Dissipation	P_{D}	400	mW
Channel Temperature	T_{ch}	150	.c <i>O</i>
Storage Temperature	$T_{ m stg}$	$-55 \sim +150$	₩°C (

■ Package Dimensions

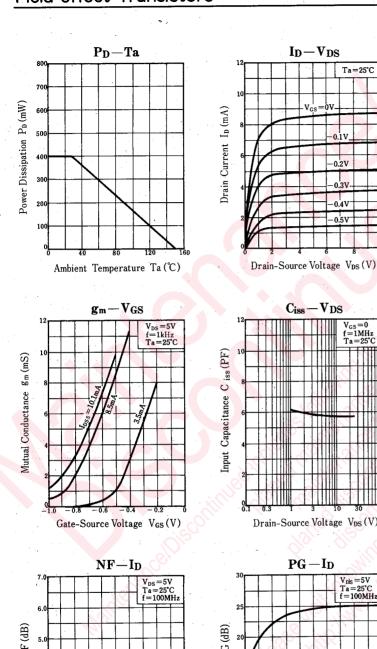


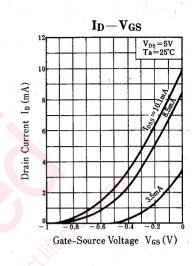
■ Electrical Characteristics (Ta=25°C)

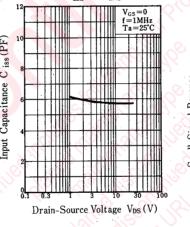
Item	Symbol	Condition	min.	typ.	max.	Unit
Gate-Drain Voltage	V_{GDO}	$I_{G} = 10 \ \mu A, \ V_{GS} = 0$	30	0	\mathcal{O}_{i}	V
Gate-Source Cutoff Voltage	V _{GSO}	$V_{DS} = 5 \text{ V}, I_{D} = 10 \mu \text{A}$		-11	-3	V
Gate Cutoff Current	I_{GSS}	$V_{GS} = -0.5 \text{ V}, V_{DS} = 0$	30	30,	10	nA
Drain Current	I _{DSS} *	$V_{DS}=5 V, V_{GS}=0$	0.5	10.	20	mA
Mutual Conductance	gm	$V_{DS} = 5 \text{ V}, V_{GS} = 0, f = 1 \text{ kHz}$	5			mS
Input Capacitance	C _{iss}	$V_{DS}=5 V$, $V_{GS}=0$, $f=1 MHz$	0	5	8	pF
Small-Signal Reverse Transfer Capacitance	C _{rss}	$V_{DS}=5 \text{ V}, I_{D}=1 \text{ mA}, f=1 \text{ MHz}$			0.3	pF
Power Gain	PG	$V_{DS} = 5 \text{ V}, \ V_{GS} = 0, \ f = 100 \text{ MHz}$	15	25		dB
Noise Figure	NF	$V_{DS} = 5 \text{ V}, V_{GS} = 0, f = 100 \text{ MHz}$		1.7	4.0	dB

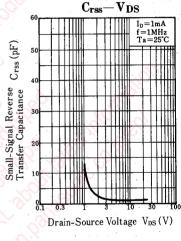
* Ipss Ranking

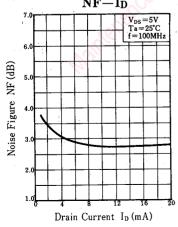
Rank	P	Q	R	S
$I_{DSS}(mA)$	0.5~3	2~7	5~12	10~20

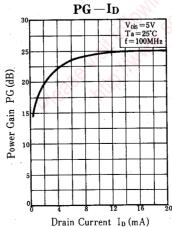


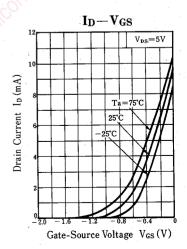












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